

Simulyzer-RT DIO-2 Card



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Safety instructions

To avoid damages to persons and devices the following safety instructions have to be noticed!

- Only qualified personnel are allowed to handle this device!
- Before any handling within the device the current supply has to be switched off!
- During operation the device have to be positioned, that enough air condition is supplied and no small parts can get into the ventilation slots.
- In case of any trouble the system has to be switched de-energized!
- The declared environmental conditions and max. voltage ranges have to be observed!
- To warranty the device remove all dust and dirt in periodically intervals.
- Make sure that the ventilation slots are unobstructed!

Intended use:

The Simulyzer RT DIO-2 card is engineered for measurement and analysis of sensors of a RT proofing system. The field of function of the DIO-2 card is the digital data transfer within the test system (see applications).

- The device is only permitted to use for the intended use.
Any other use results the deletion of the guarantee!

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Table of contents

Table of contents	3
1. Technical data	4
2. Block diagram	4
3. Connectors:.....	5
4. Interfaces and FPGA:.....	5
5. Handling card/chassis	5
6. Applications – Working modes	6
6.1. 16-times highspeed measurement application	6
6.2. 4-times comparison application	7
6.3. 16-times high-speed measurement application with different sensors	8
7. Measurement accuracy	9
7.1. Time base.....	9
7.2. Measurement of the supply voltage	9
7.3. Measurement of the supply currents.....	9
7.4. Generation of the voltages.....	9
8. Connection diagram X10/X11	10
9. Connection diagram X10/X11 as a 4x4 SPI Master Machine.....	11
10. Connection diagram SENT	12

The Simulyzer-RT DIO-2 board is a further development of the Simulyzer-RT DIO-1 board in the areas:

- Significantly higher FPGA size for the implementation of more complex processes.
- Significantly higher computing power for measured value preprocessing;
DIO-1: 100,000 signal values/s
DIO-2: 4.000.000 signal values/s

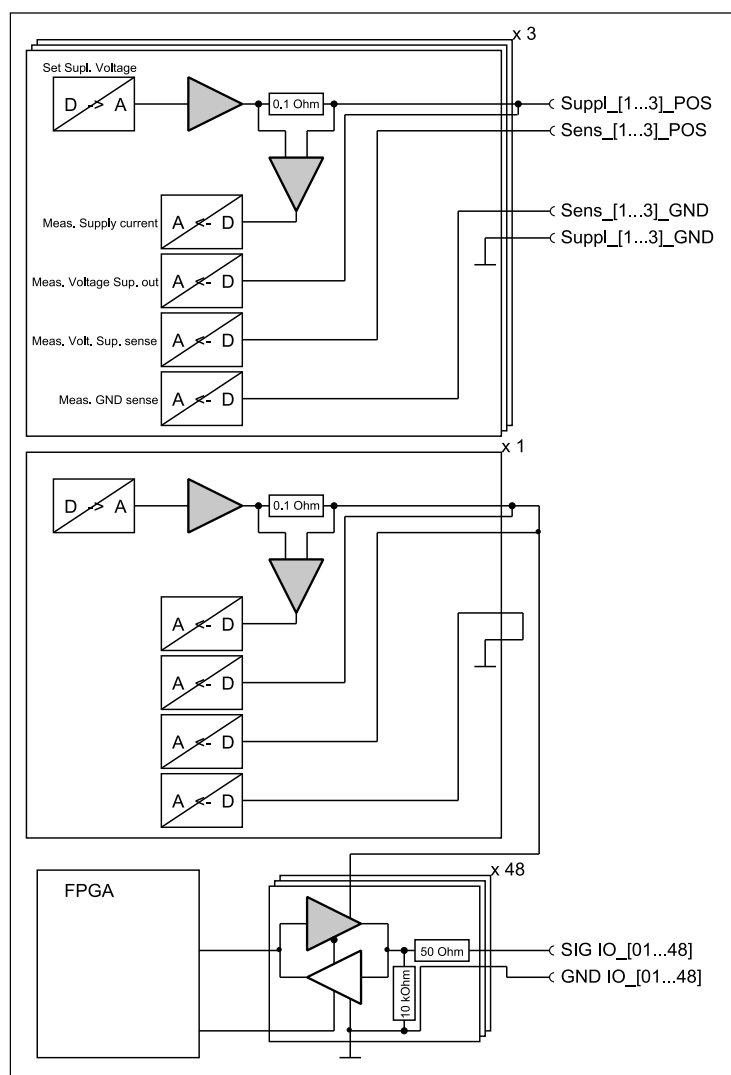
1. Technical data

- Current consumption: 12V / 0,8 A (without external consumers)
- Operating temperature: 0°C ... 40°C
- Rel. Humidity: Max. 85% not condensed
- Weight: 190g
- Dimensions: Single Eurocard, 4 U

Test conditions: Environmental temperature 20°C to 26°C

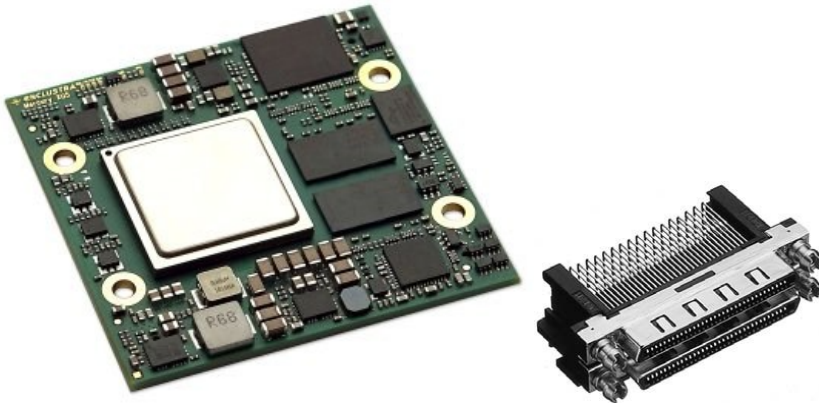
Num	Evaluation	Symbol	typ.	min.	max.	description
1	Permitted voltage range	U_{supp}	12V	11.4V	12.6V	
2	Current consumption	I_{supp}	650mA	-	800mA	Without sensor supply

2. Block diagram



3. Connectors:

- For SPI, FAST-SO
- Connectors to bus:
 - 1 PCIe Lane to CPU-1
 - Power supply I2C
 - Parallel to all cards for synchronization
- Connectors frontside: HDRA-E68W1LFDTC „Dual Stacking Connectors“ with dig IO + Sensor Power

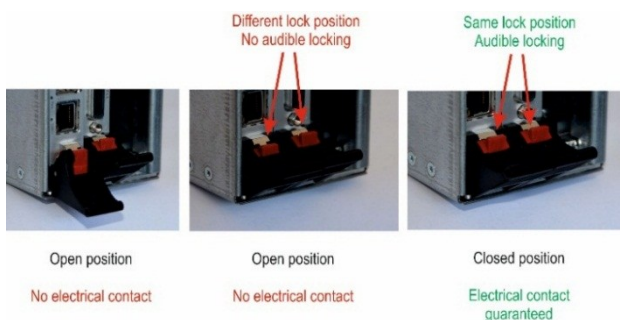


4. Interfaces and FPGA:

- Xilinx® Zynq® UltraScale+ MPSoC Modules for the realization of protocols. ARM® dual-/quad-core Cortex™-A53 (64 bit, up to 1500 MHz)
- 8 x SPI (MISO, MOSI, CS, CLK) + 16 Reserve DIG IO => 48 Pins
- 16xSPI (16xMISO, 16xMOSI, 8xCS, 8xCLK)/ 48 Pins
- With the 16 reserve IO, 4 x Fast-SO can be realized, among other things.
- All DIG IOs bidirectional, level adjustable from 1.2V to 5.5V operation; max. 20MHz
- 3x adjustable PU outputs,
 - 0.5V to 6.0V, +/- 0.1% of full scale for external supply of the sensors, current limitation 0..1000mA, +/- 0.1%.
 - 1x adjustable PU output, 0.5V to 6.0V, +/- 0.1% of full scale, current limitation 0..1000mA +/- 0.1%.
- for internal drivers (+ external)50 Ohm or 100 Ohm Impedanz Adaptation for coaxial or twisted pair lines
- Back measurement of the 4 PU voltages and the 4 currents. Accuracy: +/- 0.1% of the full scale value

5. Handling card/chassis

Pay attention that the ejection lever of the plug-in card is arrested correctly.
Only the correct position guarantees a justly connection of the bus system and the power supply!



Note

The forcible insertion of the card with displaced HF-sealing spring will damage them. As a result of that HF energy emission will be increased!

Only with intact HF-sealing spring we guarantee that the whole system confirms to the EMC guidelines.

HF-sealing spring

6. Applications – Working modes

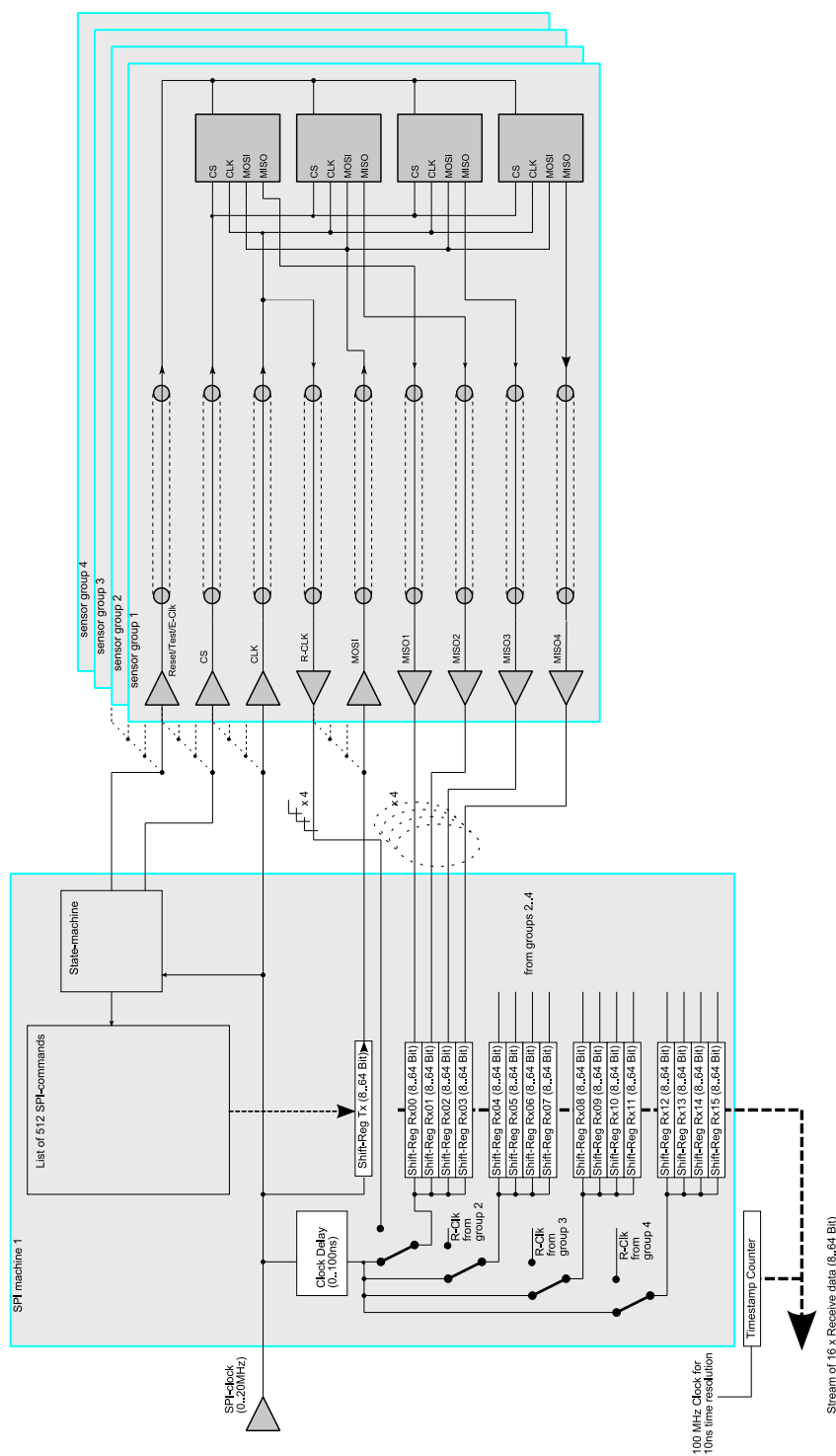
6.1. 16-times highspeed measurement application

For the application of a 16-fold-parall measurement technique a SPI machine is implemented in the FPGA, which controls the slave-in of 16 sensors together from a transmit shift register.

Chip select, clock and possibly reset/test are also controlled together.

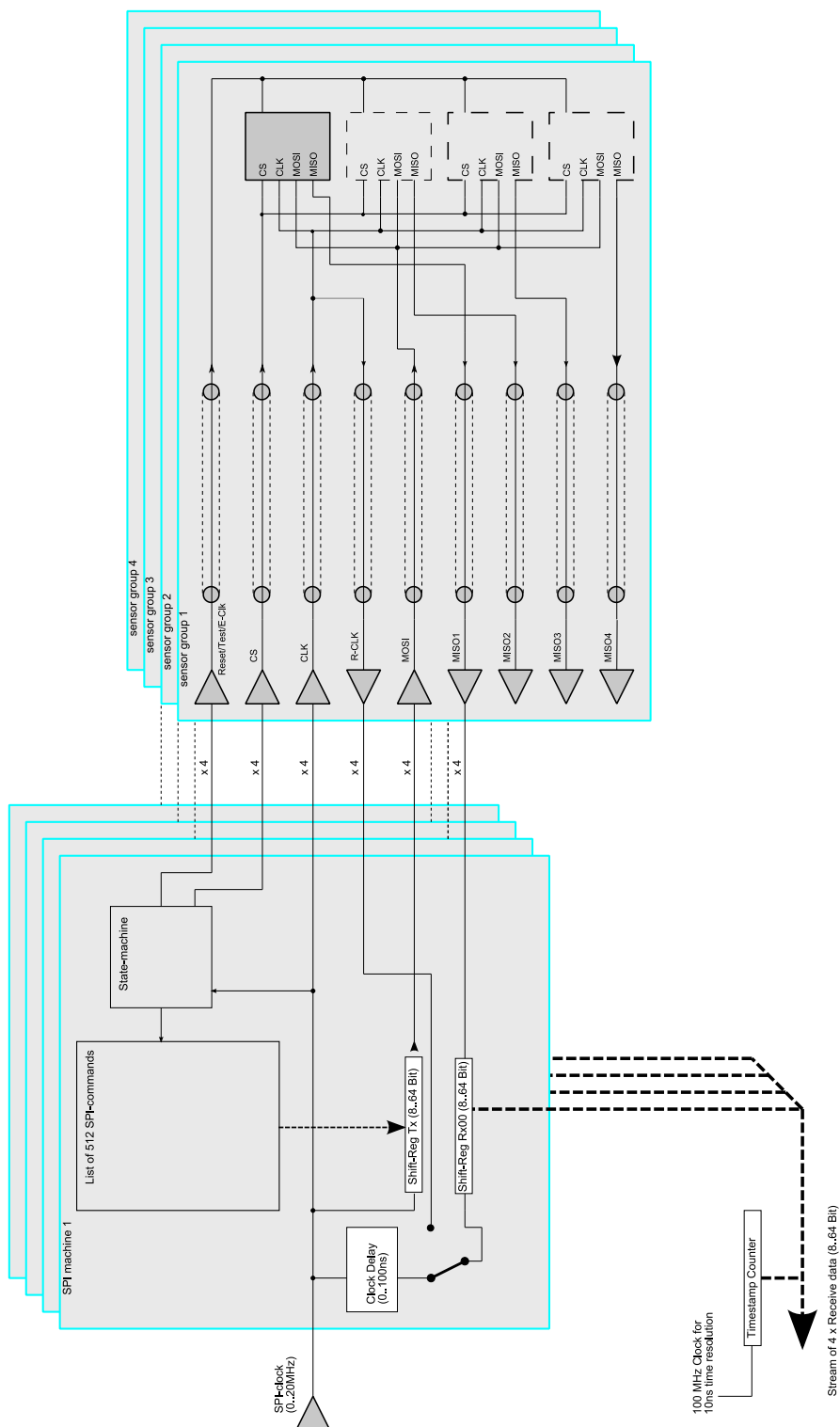
Individually implemented are the 16 slave-out lines, which go to 16 receive shift registers.

The commands go absolutely synchronously to all 16 sensors, the answers are received individually.



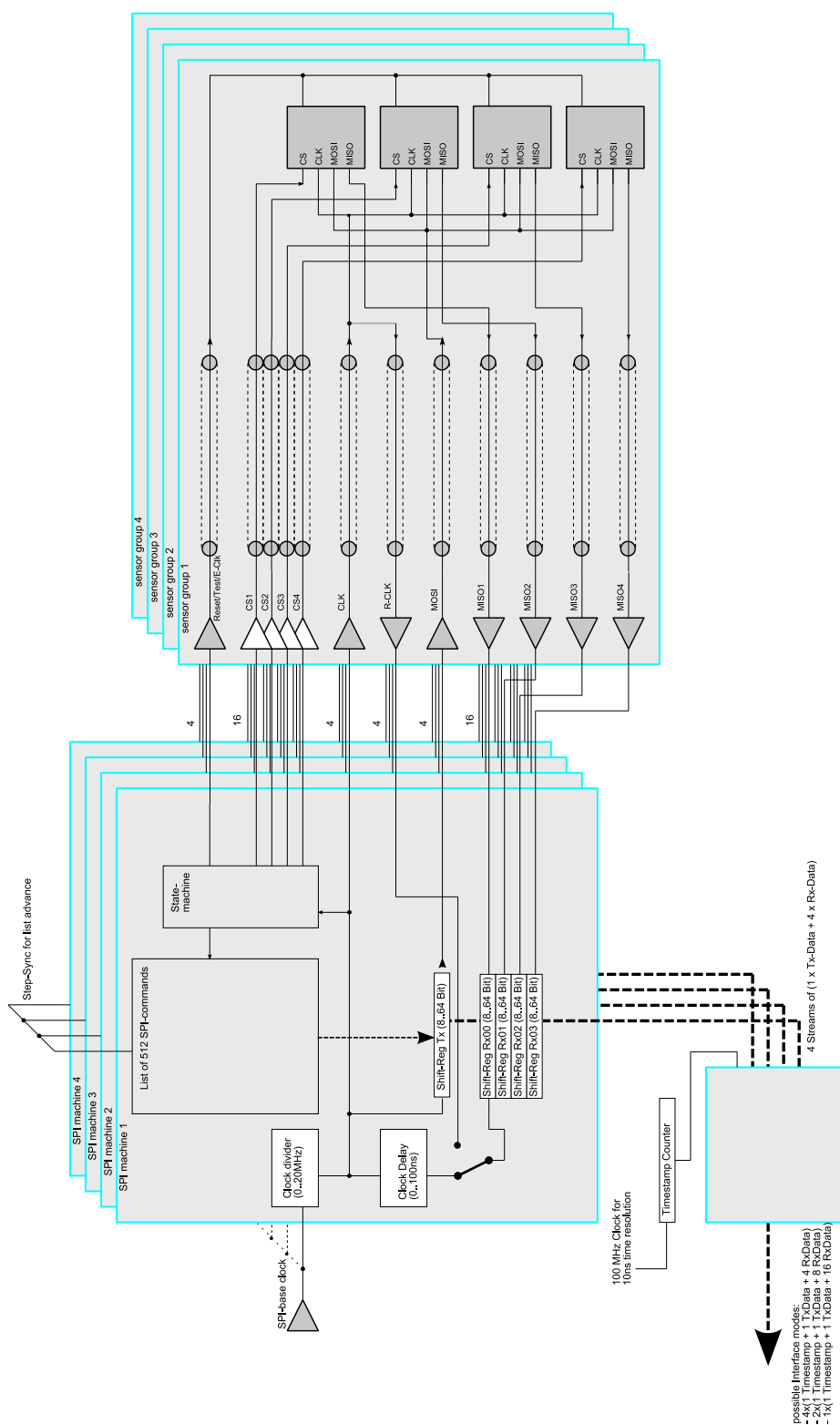
6.2. 4-times comparison application

4 SPI machines each with one own sending- and receiveing shift register.
Each SPI machine serves the first sensor of each 4 times group.
The rest of the three sensors of each group stay unpopulated.



6.3. 16-times high-speed measurement application with different sensors

At the FPGA four SPI machines are implemented, which each controls the *Slave-In* of 4 sensors of a group in common out of its 4 sending shift register. *Clock* and optionally *Reset/Test* are also controlled in common. Individually executed are the 16 *Slave-Out* lines, which are connected to the 4 receiving shift register of the 4 groups.



7. Measurement accuracy

7.1. Time base

Test conditions: Environmental temperature 20°C to 26°C						
Num	Evaluation	Symbol	Type	Max	Unit	Comment
1	Accuracy time base	$\Delta f/f$	± 30	± 50	ppm	-
2	Aging of time base	$\Delta f/f_A$	± 5		ppm/year	-
3	Temperature drift of time base	$\Delta f/f_T$	± 0.3	± 0.7	ppm/°C	-

7.2. Measurement of the supply voltage

Test conditions: Environmental temperature 20°C to 26°C						
Num	Evaluation	Symbol	Type	Max	Unit	Comment
4	Accuracy of the measured voltage	U_{mea}	± 0.3	± 0.4	% of scfin. 7.5V	Range 0.5V .. 6.0V
5	Aging of the measured voltage	U_{A-mea}		± 0.1	%/year	Range 0.5V .. 6.0V
6	Resolution of the measured voltages		16		Bit	0.. 65535
			0.1144409		mV/LSB	

7.3. Measurement of the supply currents

Test conditions: Environmental temperature 20°C to 26°C						
Num	Evaluation	Symbol	Type	Max	Unit	Comment
7	Accuracy of the measured current	I_{mea}	± 0.3	± 0.4	% of scfin. 1000mA	Range 2mA .. 900mA
8	Aging of the measured current	I_{A-mea}		± 0.1	% of scfin. 1000mA / year	Range 2mA .. 900mA
9	Resolution of the measured current		16		Bit	0.. 65535
			15,2587891		μA/LSB	

7.4. Generation of the voltages

Test conditions: Environmental temperature 20°C to 26°C						
Num	Evaluation	Symbol	Type	Max	Unit	Comment
10	Accuracy of the created current	U_{mea}	± 0.3	± 0.4	% of scfin. 6.3V	Range 0.5V .. 6.0V
11	Aging of the created current	U_{mea}		± 0.1	% of scfin 6.3V / year	Range 0.5V .. 6.0V
12	Resolution of the created current		16		Bit	0.. 65535
			0,096130371		mV/LSB	

8. Connection diagram X10/X11

Pin	Paar	Belegung Stecker 1 (Rand)
1	1	GND
35		Sig_IO 01
2	2	GND
36		Sig_IO 02
3	3	GND
37		Sig_IO 03
4	4	GND
38		Sig_IO 04
5	5	GND
39		Sig_IO 05
6	6	GND
40		Sig_IO 06
7	7	GND
41		Sig_IO 07
8	8	GND
42		Sig_IO 08
9	9	GND
43		Sig_IO 09
10	10	GND
44		Sig_IO 10
11	11	GND
45		Sig_IO 11
12	12	GND
46		Sig_IO 12
13	13	GND
47		Sig_IO 13
14	14	GND
48		Sig_IO 14
15	15	GND
49		Sig_IO 15
16	16	GND
50		Sig_IO 16
17	17	GND
51		Sig_IO 17
18	18	GND
52		Sig_IO 18
19	19	GND
53		Sig_IO 19
20	20	GND
54		Sig_IO 20
21	21	GND
55		Sig_IO 21
22	22	GND
56		Sig_IO 22
23	23	GND
57		Sig_IO 23
24	24	GND
58		Sig_IO 24
25	25	GND
59		+VCC1
26	26	GND
60		+VCC1
27	27	GND
61		+VCC1
28	28	GND
62		Sense VCC1
29	29	GND
63		Sense GND1
30	30	GND
64		+VCC2
31	31	GND
65		+VCC2
32	32	GND
66		+VCC2
33	33	GND
67		Sense VCC2
34	34	GND
68		Sense GND2

Pin	Paar	Belegung Stecker 2 (innen)
1	1	GND
35		Sig_IO 25
2	2	GND
36		Sig_IO 26
3	3	GND
37		Sig_IO 27
4	4	GND
38		Sig_IO 28
5	5	GND
39		Sig_IO 29
6	6	GND
40		Sig_IO 30
7	7	GND
41		Sig_IO 31
8	8	GND
42		Sig_IO 32
9	9	GND
43		Sig_IO 33
10	10	GND
44		Sig_IO 34
11	11	GND
45		Sig_IO 35
12	12	GND
46		Sig_IO 36
13	13	GND
47		Sig_IO 37
14	14	GND
48		Sig_IO 38
15	15	GND
49		Sig_IO 39
16	16	GND
50		Sig_IO 40
17	17	GND
51		Sig_IO 41
18	18	GND
52		Sig_IO 42
19	19	GND
53		Sig_IO 43
20	20	GND
54		Sig_IO 44
21	21	GND
55		Sig_IO 45
22	22	GND
56		Sig_IO 46
23	23	GND
57		Sig_IO 47
24	24	GND
58		Sig_IO 48
25	25	GND
59		+VCC3
26	26	GND
60		+VCC3
27	27	GND
61		+VCC3
28	28	GND
62		Sense VCC3
29	29	GND
63		Sense GND3
30	30	GND
64		+VCC4
31	31	GND
65		+VCC4
32	32	GND
66		+VCC4
33	33	GND
67		GND
34	34	GND
68		GND

9. Connection diagram X10/X11 as a 4x4 SPI Master Machine

Pin	Paar	Belegung Stecker 1 (Rand)
1	1	GND
35		CLK_G1
2	2	GND
36		R_CLK_G1
3	3	GND
37		MOSI_G1
4	4	GND
38		RES_TEST_E_G1
5	5	GND
39		CS_G1_S1
6	6	GND
40		CS_G1_S2
7	7	GND
41		CS_G1_S3
8	8	GND
42		CS_G1_S4
9	9	GND
43		MISO_G1_S1
10	10	GND
44		MISO_G1_S2
11	11	GND
45		MISO_G1_S3
12	12	GND
46		MISO_G1_S4
13	13	GND
47		CLK_G2
14	14	GND
48		R_CLK_G2
15	15	GND
49		MOSI_G2
16	16	GND
50		RES_TEST_E_G2
17	17	GND
51		CS_G2_S1
18	18	GND
52		CS_G2_S2
19	19	GND
53		CS_G2_S3
20	20	GND
54		CS_G2_S4
21	21	GND
55		MISO_G2_S1
22	22	GND
56		MISO_G2_S2
23	23	GND
57		MISO_G2_S3
24	24	GND
58		MISO_G2_S4
25	25	GND
59		+VCC1
26	26	GND
60		+VCC1
27	27	GND
61		+VCC1
28	28	GND
62		Sense VCC1
29	29	GND
63		Sense GND1
30	30	GND
64		+VCC2
31	31	GND
65		+VCC2
32	32	GND
66		+VCC2
33	33	GND
67		Sense VCC2
34	34	GND
68		Sense GND2

Pin	Paar	Belegung Stecker 2 (innen)
1	1	GND
35		CLK_G3
2	2	GND
36		R_CLK_G3
3	3	GND
37		MOSI_G3
4	4	GND
38		RES_TEST_E_G3
5	5	GND
39		CS_G3_S1
6	6	GND
40		CS_G3_S2
7	7	GND
41		CS_G3_S3
8	8	GND
42		CS_G3_S4
9	9	GND
43		MISO_G3_S1
10	10	GND
44		MISO_G3_S2
11	11	GND
45		MISO_G3_S3
12	12	GND
46		MISO_G3_S4
13	13	GND
47		CLK_G4
14	14	GND
48		R_CLK_G4
15	15	GND
49		MOSI_G4
16	16	GND
50		RES_TEST_E_G4
17	17	GND
51		CS_G4_S1
18	18	GND
52		CS_G4_S2
19	19	GND
53		CS_G4_S3
20	20	GND
54		CS_G4_S4
21	21	GND
55		MISO_G4_S1
22	22	GND
56		MISO_G4_S2
23	23	GND
57		MISO_G4_S3
24	24	GND
58		MISO_G4_S4
25	25	GND
59		+VCC3
26	26	GND
60		+VCC3
27	27	GND
61		+VCC3
28	28	GND
62		Sense VCC3
29	29	GND
63		Sense GND3
30	30	GND
64		+VCC4
31	31	GND
65		+VCC4
32	32	GND
66		+VCC4
33	33	GND
67		GND
34	34	GND
68		GND

10. Connection diagram SENT

Pin	Paar	Belegung Stecker 1 (Rand)
1	1	GND
35		SENT 01
2	2	GND
36		SENT 02
3	3	GND
37		SENT 03
4	4	GND
38		SENT 04
5	5	GND
39		SENT 05
6	6	GND
40		SENT 06
7	7	GND
41		SENT 07
8	8	GND
42		SENT 08
9	9	GND
43		SENT 09
10	10	GND
44		SENT 10
11	11	GND
45		SENT 11
12	12	GND
46		SENT 12
13	13	GND
47		SENT 13
14	14	GND
48		SENT 14
15	15	GND
49		SENT 15
16	16	GND
50		SENT 16
17	17	GND
51		SENT 17
18	18	GND
52		SENT 18
19	19	GND
53		S_0
20	20	GND
54		S_1
21	21	GND
55		S_2
22	22	GND
56		S_3
23	23	GND
57		
24	24	GND
58		External SampleEnable
25	25	GND
59		+VCC1
26	26	GND
60		+VCC1
27	27	GND
61		+VCC1
28	28	GND
62		Sense VCC1
29	29	GND
63		Sense GND1
30	30	GND
64		+VCC2
31	31	GND
65		+VCC2
32	32	GND
66		+VCC2
33	33	GND
67		Sense VCC2
34	34	GND
68		Sense GND2

Pin	Paar	Belegung Stecker 2 (innen)
1	1	GND
35		SENT 19
2	2	GND
36		SENT 20
3	3	GND
37		SENT 21
4	4	GND
38		SENT 22
5	5	GND
39		SENT 23
6	6	GND
40		SENT24
7	7	GND
41		SENT 25
8	8	GND
42		SENT 26
9	9	GND
43		SENT 27
10	10	GND
44		SENT 28
11	11	GND
45		SENT 29
12	12	GND
46		SENT 30
13	13	GND
47		SENT 31
14	14	GND
48		SENT 32
15	15	GND
49		SENT 33
16	16	GND
50		SENT 34
17	17	GND
51		SENT 35
18	18	GND
52		SENT 36
19	19	GND
53		S_0
20	20	GND
54		S_1
21	21	GND
55		S_2
22	22	GND
56		S_3
23	23	GND
57		
24	24	GND
58		External SampleEnable
25	25	GND
59		+VCC3
26	26	GND
60		+VCC3
27	27	GND
61		+VCC3
28	28	GND
62		Sense VCC3
29	29	GND
63		Sense GND3
30	30	GND
64		+VCC4
31	31	GND
65		+VCC4
32	32	GND
66		+VCC4
33	33	GND
67		
34	34	GND
68		